

TOSHIBA CMOS Digital Integrated Circuit Silicon Monolithic

**TC74AC08P, TC74AC08F, TC74AC08FN, TC74AC08FT****Quad 2-Input AND Gate**

The TC74AC08 is an advanced high speed CMOS 2-INPUT AND GATE fabricated with silicon gate and double-layer metal wiring C<sup>2</sup>MOS technology.

It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

The internal circuit is composed of 2 stages including buffer output, which provide high noise immunity and stable output.

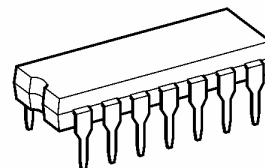
All inputs are equipped with protection circuits against static discharge or transient excess voltage.

**Features**

- High speed:  $t_{pd} = 3.4 \text{ ns}$  (typ.) at  $V_{CC} = 5 \text{ V}$
- Low power dissipation:  $I_{CC} = 4 \mu\text{A}$  (max) at  $T_a = 25^\circ\text{C}$
- High noise immunity:  $V_{NIH} = V_{NIL} = 28\% V_{CC}$  (min)
- Symmetrical output impedance:  
 $|I_{OH}| = I_{OL} = 24 \text{ mA}$  (min)  
 Capability of driving  $50 \Omega$  transmission lines.
- Balanced propagation delays:  $t_{pLH} \approx t_{pHL}$
- Wide operating voltage range:  $V_{CC} \text{ (opr)} = 2 \text{ V to } 5.5 \text{ V}$
- Pin and function compatible with 74F08

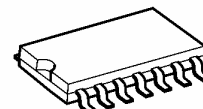
Note: xxxFN (JEDEC SOP) is not available in Japan.

TC74AC08P

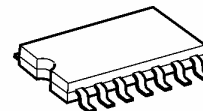


DIP14-P-300-2.54

TC74AC08F

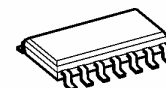


SOP14-P-300-1.27A



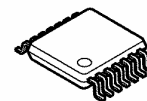
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TC74AC08FN



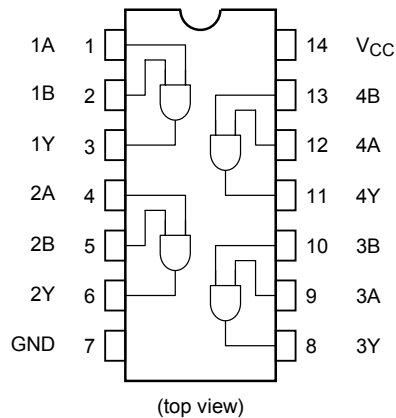
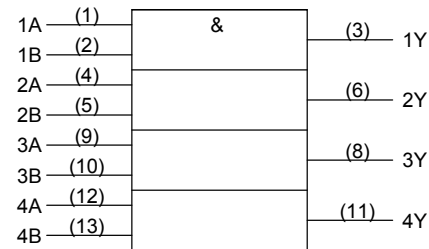
SOL14-P-150-1.27

TC74AC08FT



TSSOP14-P-0044-0.65A

Weight	
DIP14-P-300-2.54	: 0.96 g (typ.)
SOP14-P-300-1.27A	: 0.18 g (typ.)
SOP14-P-300-1.27	: 0.18 g (typ.)
SOL14-P-150-1.27	: 0.12 g (typ.)
TSSOP14-P-0044-0.65A	: 0.06 g (typ.)

**Pin Assignment****IEC Logic Symbol****Truth Table**

A	B	Y
L	L	L
L	H	L
H	L	L
H	H	H

**Absolute Maximum Ratings (Note 1)**

Characteristics	Symbol	Rating	Unit
Supply voltage range	$V_{CC}$	-0.5 to 7.0	V
DC input voltage	$V_{IN}$	-0.5 to $V_{CC} + 0.5$	V
DC output voltage	$V_{OUT}$	-0.5 to $V_{CC} + 0.5$	V
Input diode current	$I_{IK}$	$\pm 20$	mA
Output diode current	$I_{OK}$	$\pm 50$	mA
DC output current	$I_{OUT}$	$\pm 50$	mA
DC $V_{CC}$ /ground current	$I_{CC}$	$\pm 100$	mA
Power dissipation	$P_D$	500 (DIP) (Note 2)/180 (SOP/TSSOP)	mW
Storage temperature	$T_{stg}$	-65 to 150	$^{\circ}C$

Note1: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Note2: 500 mW in the range of  $T_a = -40^{\circ}C$  to  $65^{\circ}C$ . From  $T_a = 65^{\circ}C$  to  $85^{\circ}C$  a derating factor of  $-10$  mW/ $^{\circ}C$  should be applied up to 300 mW.

**Recommended Operating Conditions (Note)**

Characteristics	Symbol	Rating	Unit
Supply voltage	$V_{CC}$	2.0 to 5.5	V
Input voltage	$V_{IN}$	0 to $V_{CC}$	V
Output voltage	$V_{OUT}$	0 to $V_{CC}$	V
Operating temperature	$T_{opr}$	-40 to 85	°C
Input rise and fall time	dt/dV	0 to 100 ( $V_{CC} = 3.3 \pm 0.3$ V) 0 to 20 ( $V_{CC} = 5 \pm 0.5$ V)	ns/V

Note: The recommended operating conditions are required to ensure the normal operation of the device.  
Unused inputs must be tied to either  $V_{CC}$  or GND.

**Electrical Characteristics****DC Characteristics**

Characteristics	Symbol	Test Condition	$T_a = 25^\circ\text{C}$			$T_a = -40 \text{ to } 85^\circ\text{C}$		Unit		
			$V_{CC}$ (V)	Min	Typ.	Max	Min		Max	
High-level input voltage	$V_{IH}$	—	2.0	1.50	—	—	1.50	—	V	
			3.0	2.10	—	—	2.10	—		
			5.5	3.85	—	—	3.85	—		
Low-level input voltage	$V_{IL}$	—	2.0	—	—	0.50	—	0.50	V	
			3.0	—	—	0.90	—	0.90		
			5.5	—	—	1.65	—	1.65		
High-level output voltage	$V_{OH}$	$V_{IN} = V_{IH}$	$I_{OH} = -50 \mu\text{A}$	2.0	1.9	2.0	—	1.9	—	V
				3.0	2.9	3.0	—	2.9	—	
			$I_{OH} = -4 \text{ mA}$	3.0	2.58	—	—	2.48	—	
			$I_{OH} = -24 \text{ mA}$	4.5	3.94	—	—	3.80	—	
Low-level output voltage	$V_{OL}$	$V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OL} = 50 \mu\text{A}$	2.0	—	0.0	0.1	—	0.1	V
				3.0	—	0.0	0.1	—	0.1	
				4.5	—	0.0	0.1	—	0.1	
			$I_{OL} = 12 \text{ mA}$	3.0	—	—	0.36	—	0.44	
			$I_{OL} = 24 \text{ mA}$	4.5	—	—	0.36	—	0.44	
			$I_{OL} = 75 \text{ mA}$ (Note)	5.5	—	—	—	—	1.65	
Input leakage current	$I_{IN}$	$V_{IN} = V_{CC}$ or GND	5.5	—	—	$\pm 0.1$	—	$\pm 1.0$	$\mu\text{A}$	
Quiescent supply current	$I_{CC}$	$V_{IN} = V_{CC}$ or GND	5.5	—	—	4.0	—	40.0	$\mu\text{A}$	

Note: This spec indicates the capability of driving 50  $\Omega$  transmission lines.

One output should be tested at a time for a 10 ms maximum duration.

**AC Characteristics ( $C_L = 50 \text{ pF}$ ,  $R_L = 500 \text{ } \Omega$ , input:  $t_r = t_f = 3 \text{ ns}$ )**

Characteristics	Symbol	Test Condition	Ta = 25°C			Ta = -40 to 85°C		Unit	
			V <sub>CC</sub> (V)	Min	Typ.	Max	Min		Max
Propagation delay time	t <sub>pLH</sub>	—	3.3 ± 0.3	—	5.8	9.8	1.0	11.3	ns
	t <sub>pHL</sub>		5.0 ± 0.5	—	4.5	7.0	1.0	8.0	
Input capacitance	C <sub>IN</sub>	—	—	5	10	—	10	pF	
Power dissipation capacitance	C <sub>PD</sub>	(Note)	—	71	—	—	—	pF	

Note: C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

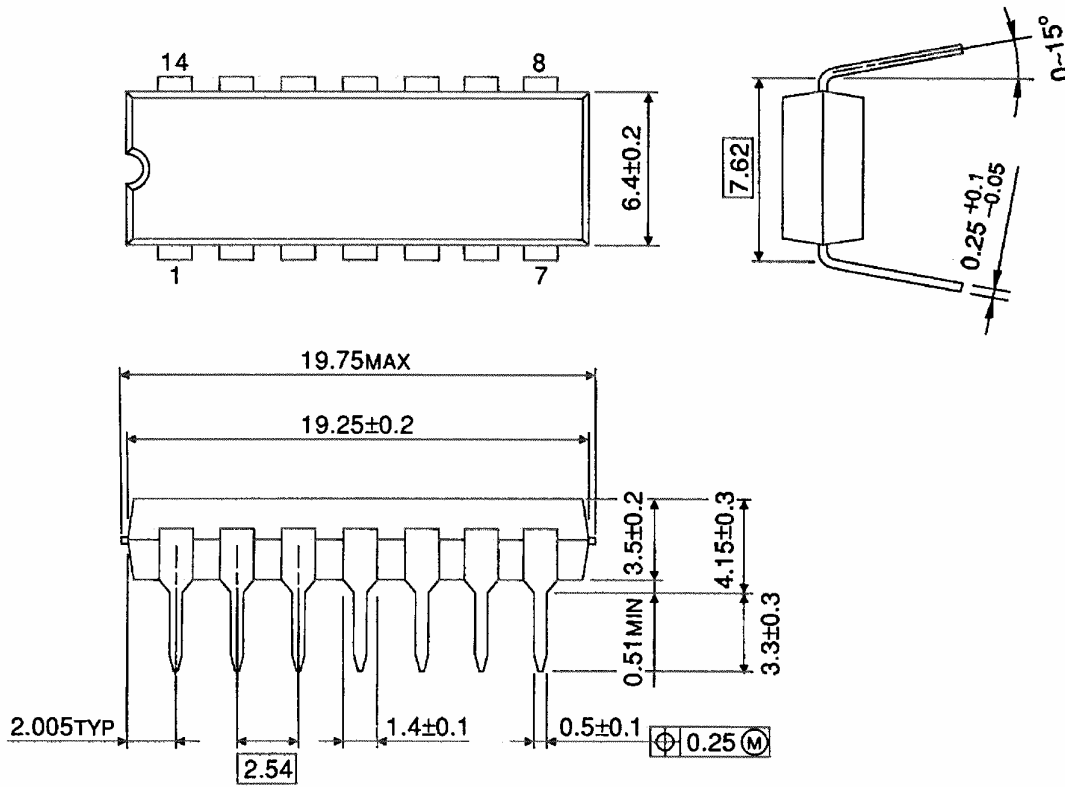
Average operating current can be obtained by the equation:

$$I_{CC (opr)} = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}/4 \text{ (per gate)}$$

### Package Dimensions

DIP14-P-300-2.54

Unit : mm

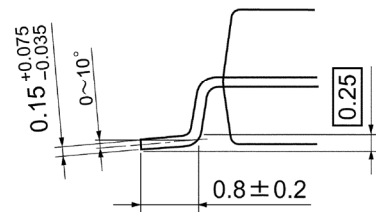
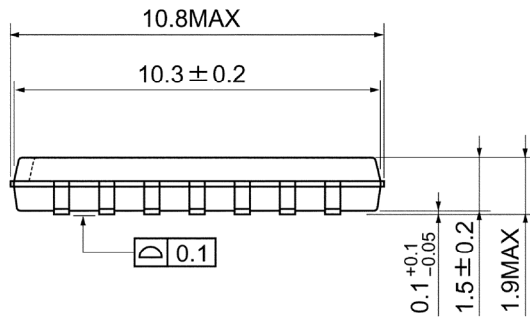
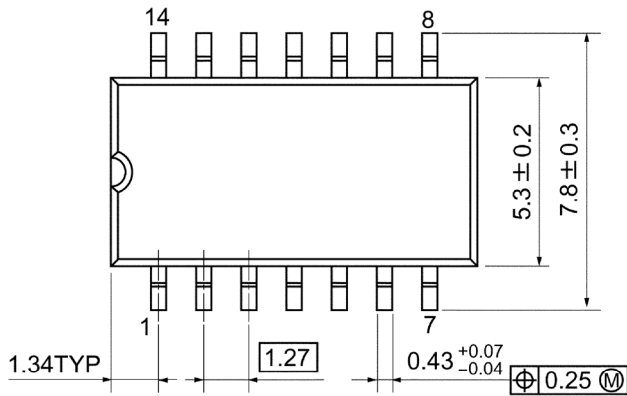


Weight: 0.96 g (typ.)

## Package Dimensions

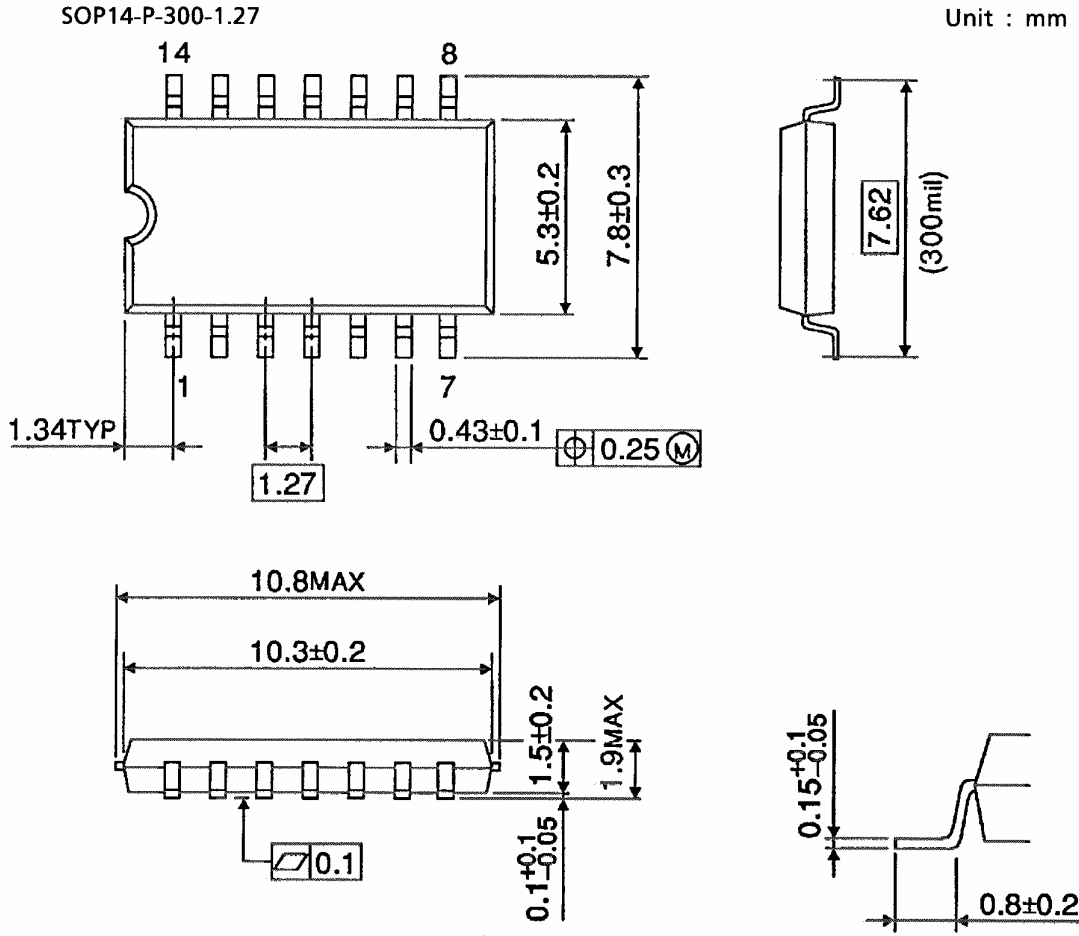
SOP14-P-300-1.27A

Unit: mm



Weight: 0.18 g (typ.)

### Package Dimensions

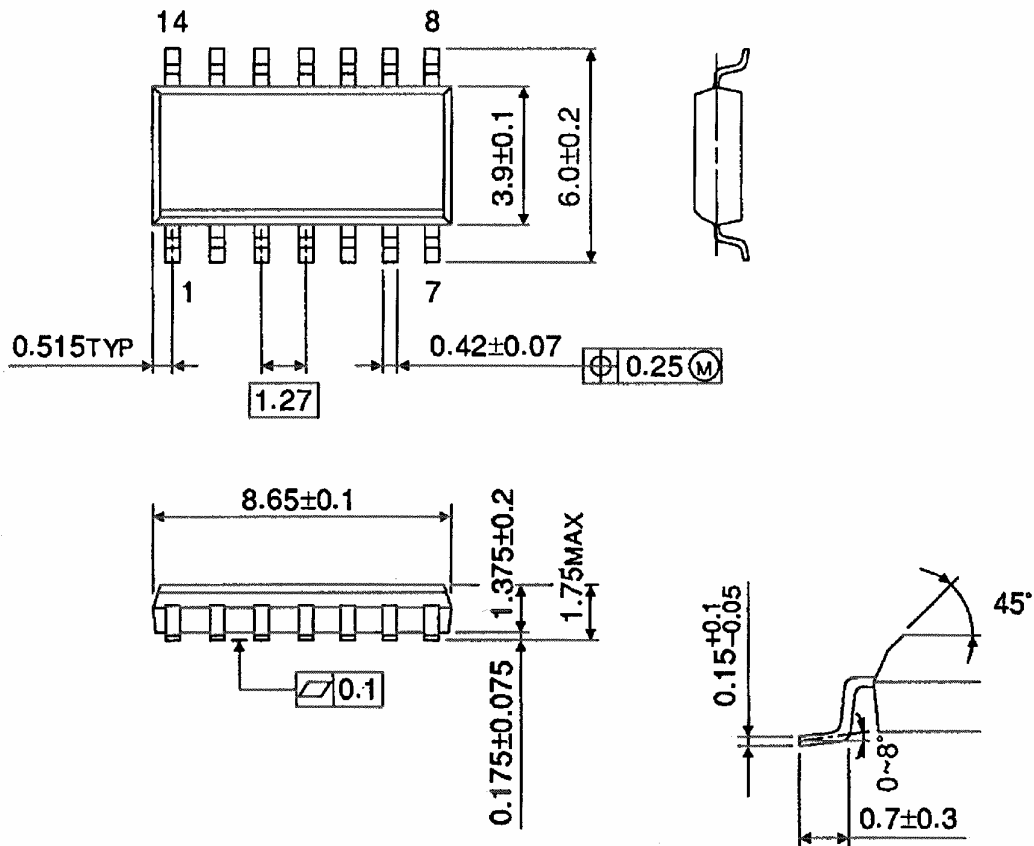


Weight: 0.18 g (typ.)

**Package Dimensions (Note)**

SOL14-P-150-1.27

Unit : mm



Note: This package is not available in Japan.

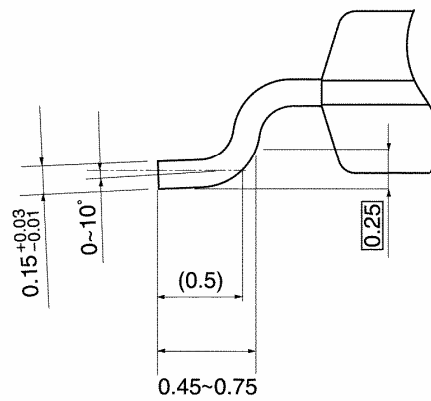
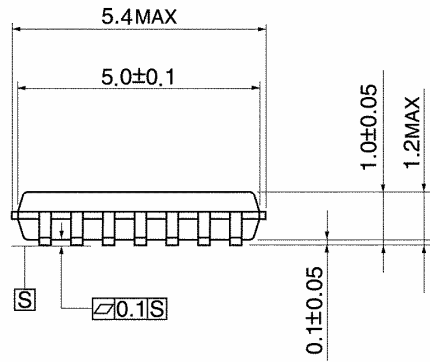
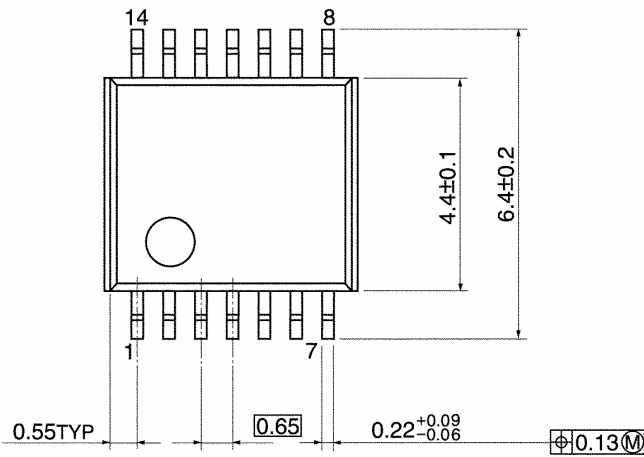
Weight: 0.12 g (typ.)



## Package Dimensions

TSSOP14-P-0044-0.65A

Unit: mm



Weight: 0.06 g (typ.)

**Note: Lead (Pb)-Free Packages****DIP14-P-300-2.54 SOP14-P-300-1.27A SOL14-P-150-1.27 TSSOP14-P-0044-0.65A****RESTRICTIONS ON PRODUCT USE**

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